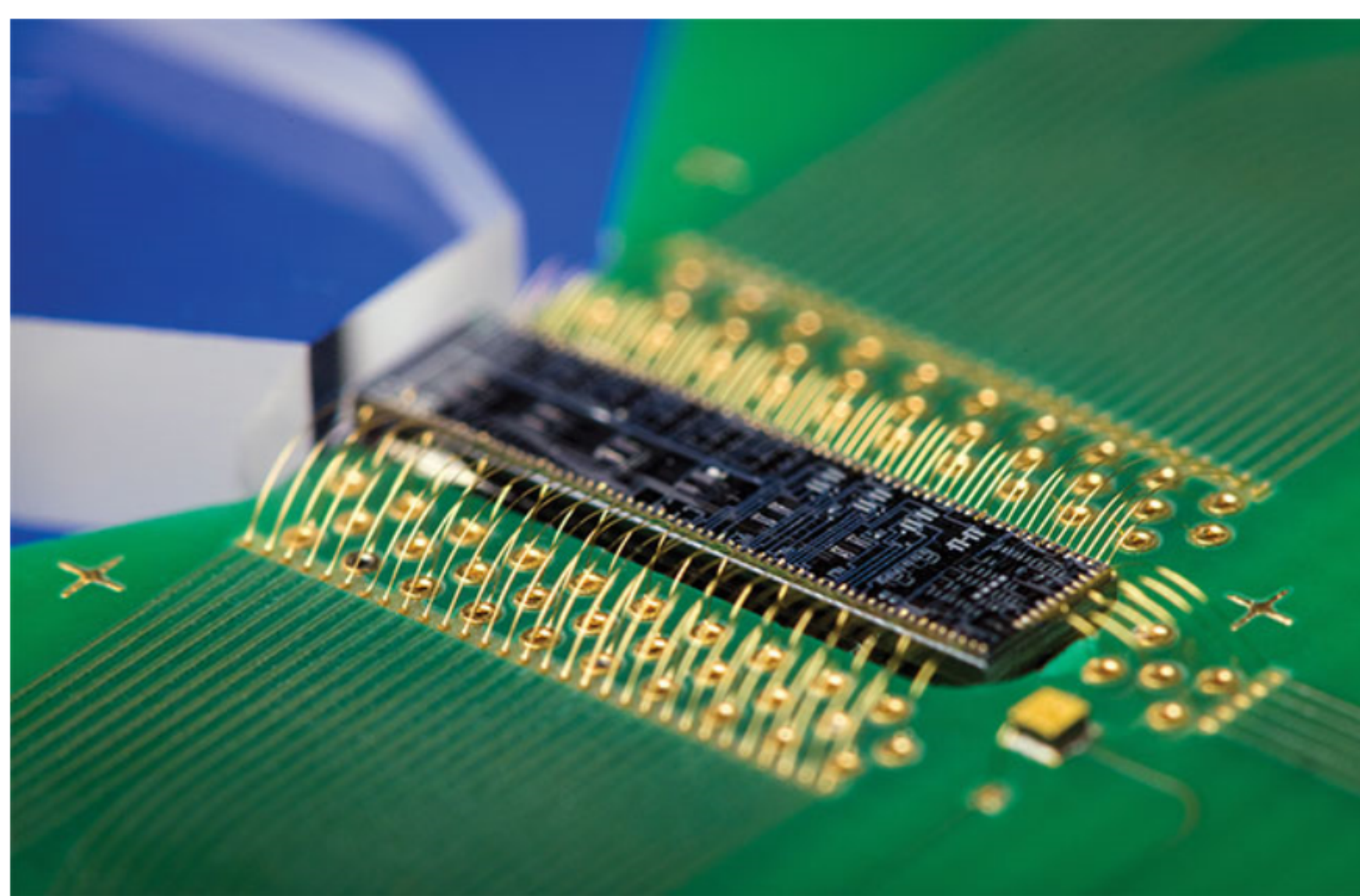
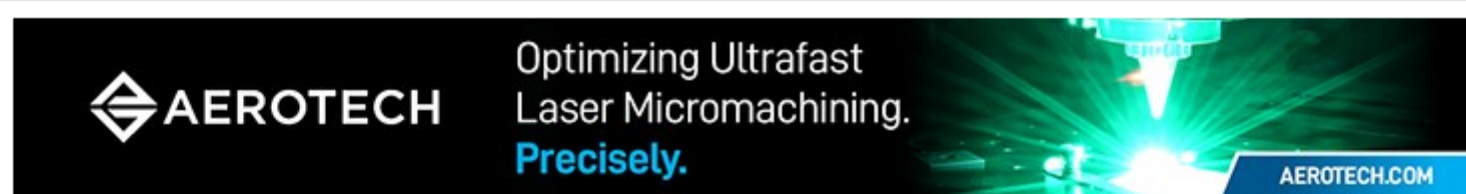




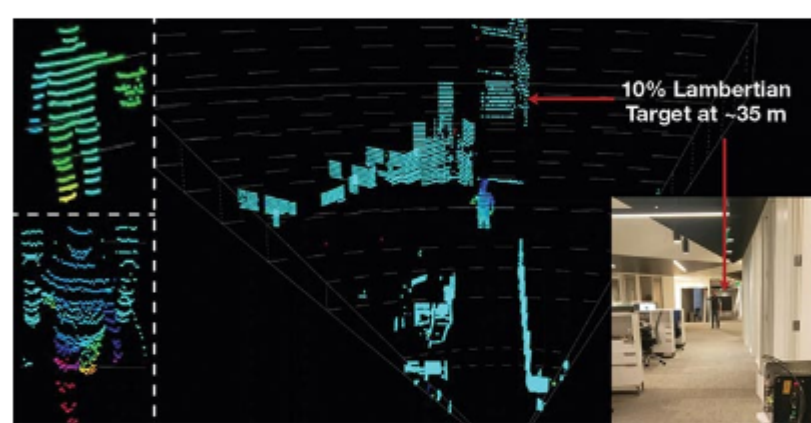
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**Five Common Design Mistakes Can Send PIC Packaging Costs Skyrocketing**

We have all heard that photonic integrated circuits (PICs) can pack a ton of functionality into high-performance, energy-efficient, and low-cost microchips, as well as the promise that they will enable a revolution of powerful optoelectronic devices for a host of applications. However, the complexity of transforming chips into functional devices is often underestimated and the cost of PIC packaging can take a notoriously big chunk out of the development budget.

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**Nikon Corp., Digital Solutions Business Unit**

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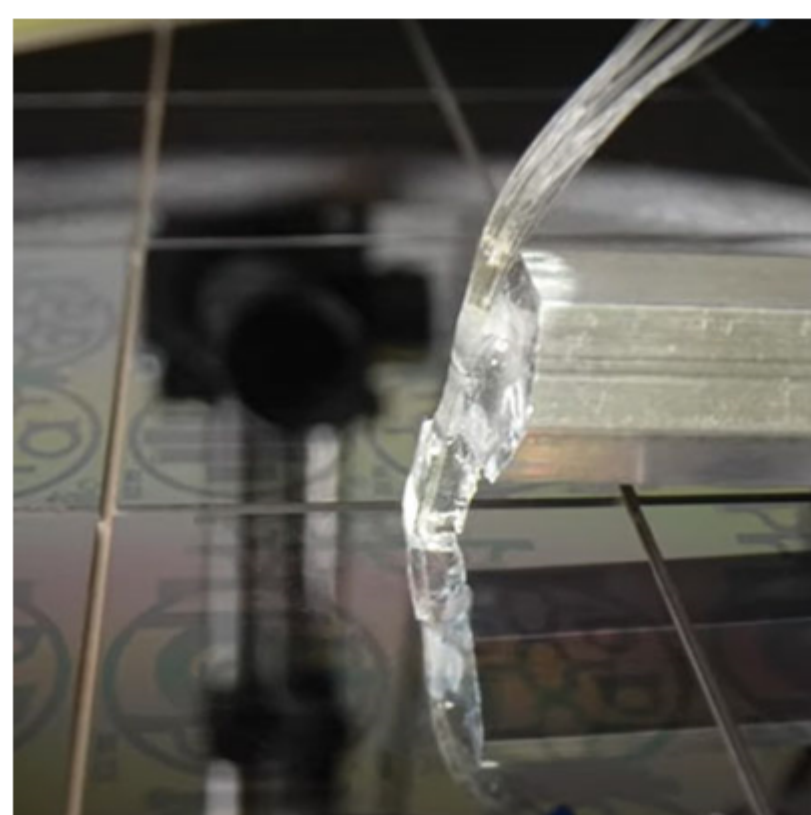
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